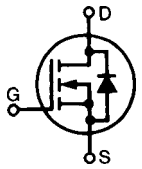
IXYS

HiPerFET™ Power MOSFETs Q-Class

IXFH 15N80Q
IXFT 15N80Q

V_{DSS} = 800 V
I_{D25} = 15 A
$R_{DS(on)}$ = 0.60 Ω
$t_{rr} \leq$ 250 ns

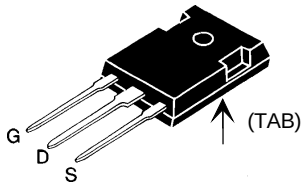
N-Channel Enhancement Mode
Avalanche Rated, High dv/dt, Low Q_g



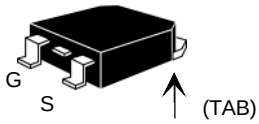
Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	800	V
V_{DGR}	T_J = 25°C to 150°C; R_{GS} = 1 MΩ	800	V
V_{GS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C	15	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	60	A
I_{AR}	T_C = 25°C	15	A
E_{AR}	T_C = 25°C	30	mJ
E_{AS}	T_C = 25°C	1.0	J
dv/dt	$I_S \leq I_{DM}$, di/dt ≤ 100 A/μs, $V_{DD} \leq V_{DSS}$, $T_J \leq$ 150°C, R_G = 2 Ω	5	V/ns
P_D	T_C = 25°C	300	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6 mm (0.062 in.) from case for 10 s	300	°C
M_d	Mounting torque	1.13/10	Nm/lb.in.
Weight	TO-247	6	g
	TO-268	4	g

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)		Characteristic Values Min.	Typ.	Max.	
V_{DSS}	V_{GS} = 0 V, I_D = 3 mA		800			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 4 mA		2.0		4.5	V
I_{GSS}	V_{GS} = ±20 V_{DC}, V_{DS} = 0				±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$	T_J = 25°C			25	μA
	V_{GS} = 0 V	T_J = 125°C			1	mA
$R_{DS(on)}$	V_{GS} = 10 V, I_D = 0.5 I_{D25} Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %				0.60	Ω

TO-247 AD (IXFH)



TO-268 (D3) (IXFT) Case Style



G = Gate D = Drain
S = Source TAB = Drain

Features

- IXYS advanced low Q_g process
- International standard packages
- Low $R_{DS\ (on)}$
- Unclamped Inductive Switching (UIS) rated
- Fast switching
- Molding epoxies meet UL 94 V-0 flammability classification

Advantages

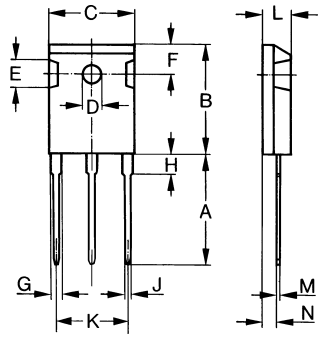
- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10 V; I_D = 0.5 I_{D25}, pulse test	8	16		S
C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		4300		pF
C_{oss}			360		pF
C_{rss}			60		pF
$t_{d(on)}$	V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25} R_G = 1.5 Ω (External)		18		ns
t_r			27		ns
$t_{d(off)}$			53		ns
t_f			16		ns
$Q_{g(on)}$	V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}		90		nC
Q_{gs}			20		nC
Q_{gd}			30		nC
R_{thJC}				0.42	K/W
R_{thCK}	(TO-247)		0.25		K/W

Source-Drain Diode

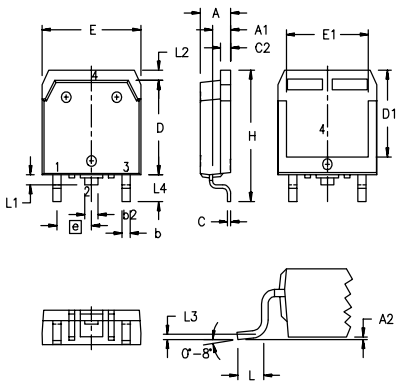
Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
I_S	V_{GS} = 0 V			15	A
I_{SM}	Repetitive;			60	A
V_{SD}	$I_F = I_S$, V_{GS} = 0 V, Pulse test, t ≤ 300 µs, duty cycle d ≤ 2 %			1.5	V
t_{rr}	$I_F = I_S$-di/dt = 100 A/µs, V_R = 100 V			250	ns
Q_{RM}			0.85		µC
I_{RM}			8		A

TO-247 AD (IXFH) Outline



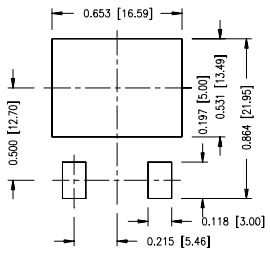
Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

TO-268AA (D^3 PAK)



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.9	5.1	.193	.201
A_1	2.7	2.9	.106	.114
A_2	.02	.25	.001	.010
b	1.15	1.45	.045	.057
b_2	1.9	2.1	.75	.83
C	.4	.65	.016	.026
D	13.80	14.00	.543	.551
E	15.85	16.05	.624	.632
E_1	13.3	13.6	.524	.535
e	5.45 BSC		.215 BSC	
H	18.70	19.10	.736	.752
L	2.40	2.70	.094	.106
L1	1.20	1.40	.047	.055
L2	1.00	1.15	.039	.045
L3	0.25 BSC		.010 BSC	
L4	3.80	4.10	.150	.161

Min. Recommended Footprint



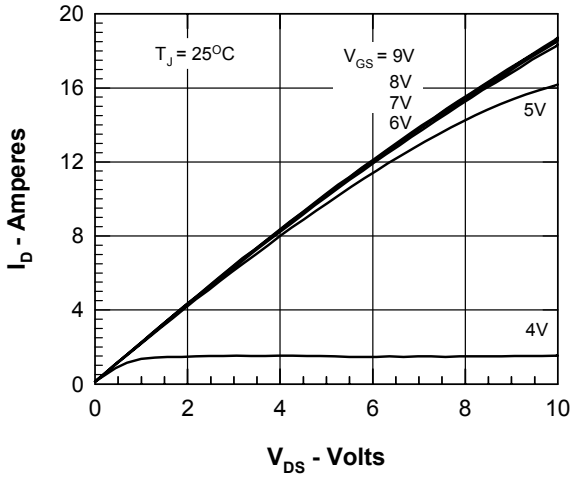


Figure 1. Output Characteristics at 25°C

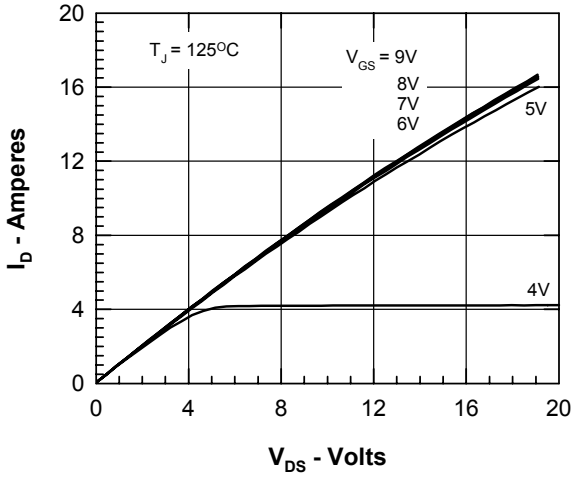


Figure 2. Output Characteristics at 125°C

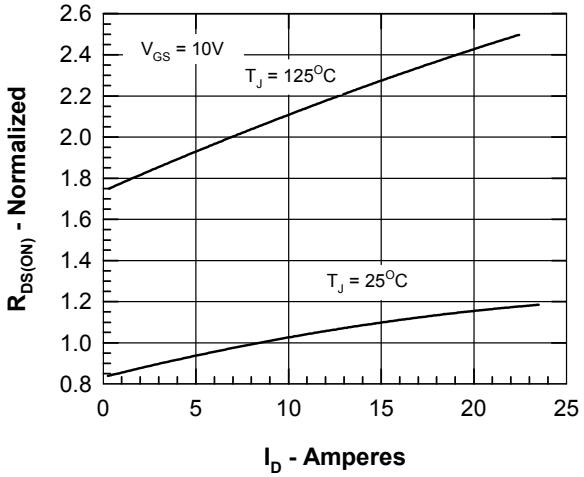


Figure 3. $R_{DS(on)}$ normalized to value at I_D = 12A

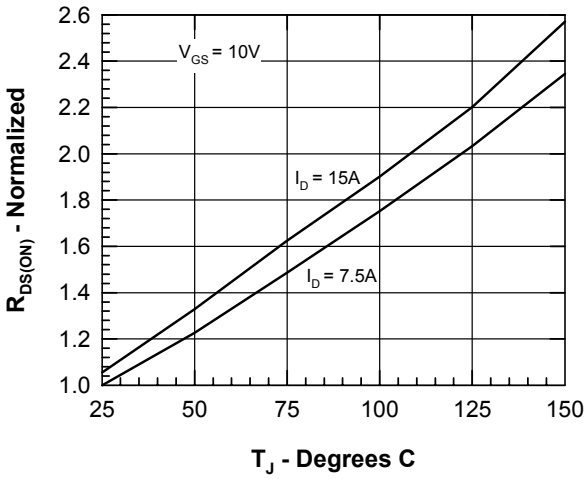


Figure 4. $R_{DS(on)}$ normalized to value at I_D = 12A

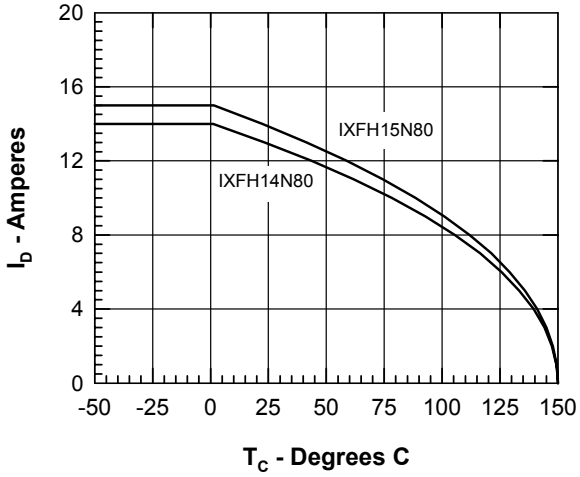


Figure 5. Drain Current vs. Case Temperature

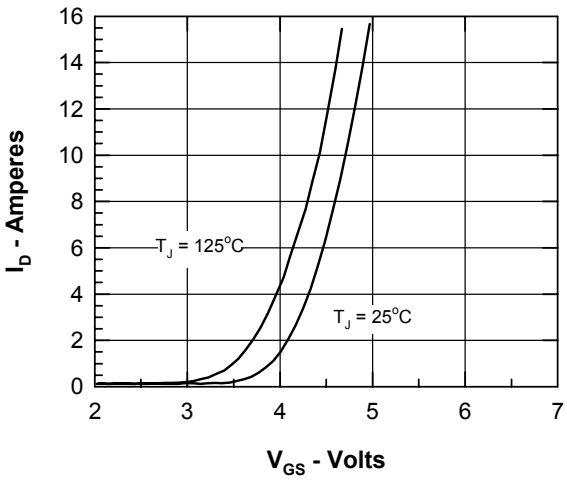


Figure 6. Admittance Curves

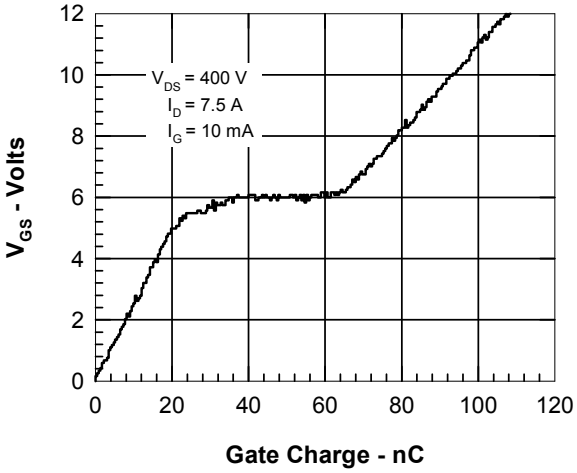


Figure 7. Gate Charge

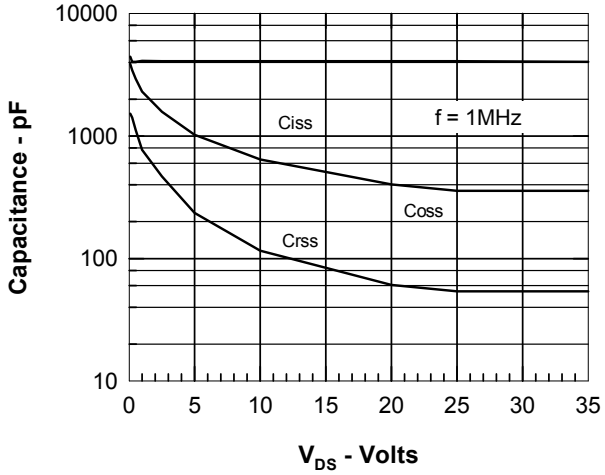


Figure 8. Capacitance Curves

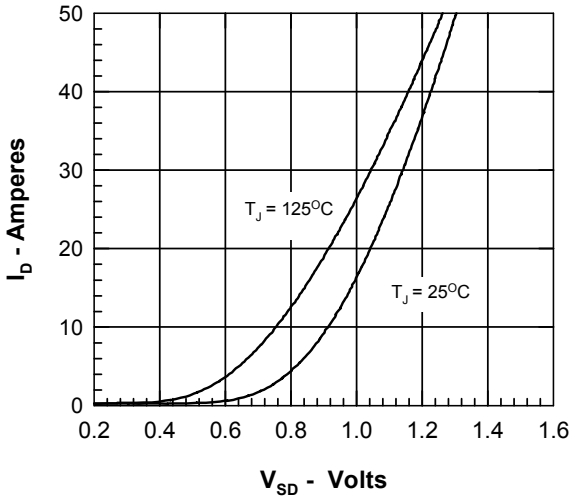


Figure 9. Source Current vs. Source to Drain Voltage

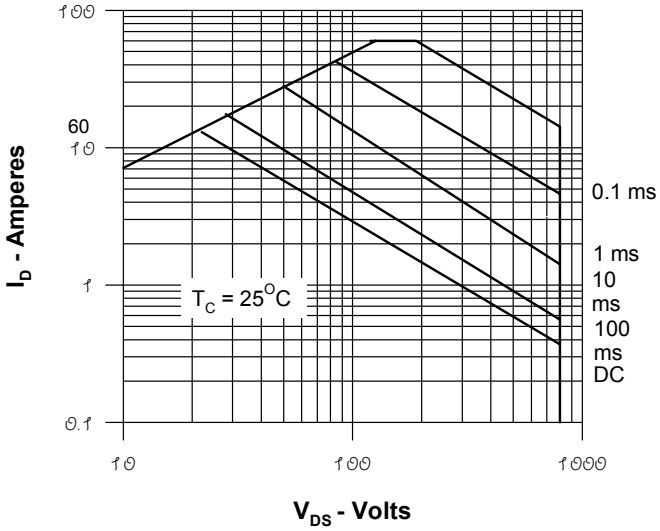


Figure10. Forward Bias Safe Operating Area

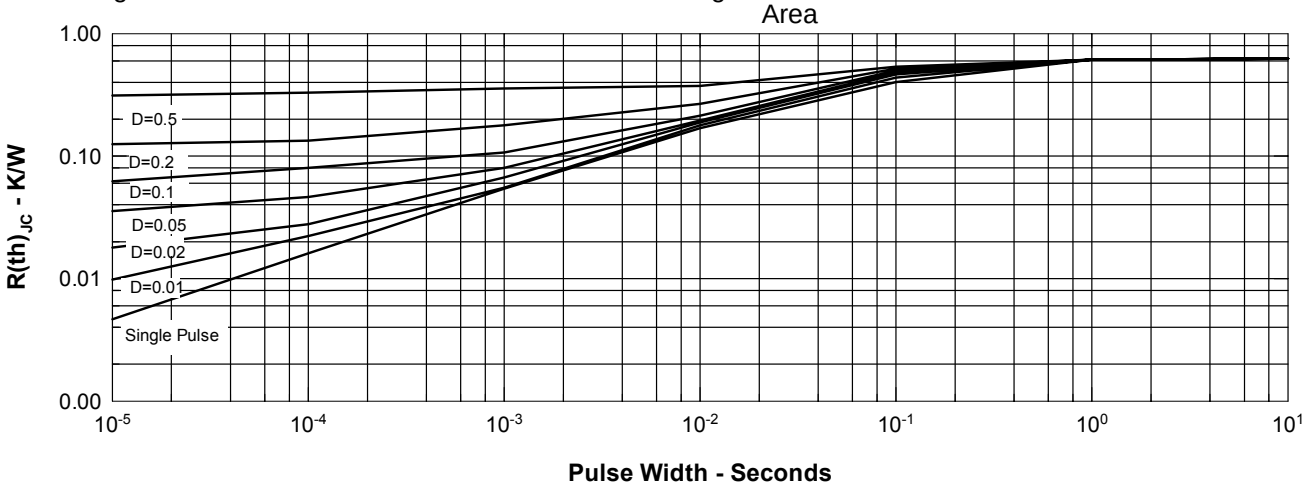


Figure 11. Transient Thermal Resistance